SENSING
THE
BEAUTIFUL LIFE

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MEMSIC

MEMSIC Semiconductor is a world-leading IC product company, mainly engaged in MEMS sensor R&D, manufacturing and sales, providing "one-stop" sensor solutions of MEMS sensor chip, software algorithm and applications. MEMSIC now realizes large-scale production of world's most exclusive thermal accelerometer, AMR geomagnetic sensor, capacitive accelerometer, and micropower Hall Switch, that are widely applied to different fields such as automobile, industrial, medical, wearable, smart home, and consumer electronics.

AMR 3D Magnetometer

Ultra-Small

Low Noise

High Sensitivity

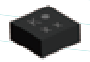
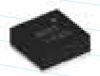
High Accuracy


History of MEMSIC Magnetometers


Mobile & Tablets


Automotive Infotainment


Drone

MMC5633NJL MMC5616WA	• Monolithic integrated 3-axis magnetometers • Advanced AMR technology • Wafer level package size: 0.8×0.8×0.4mm • MMC5633NJL fully supports I3C interfaces	
MMC3630KJ	• Mature process, stable and reliable performance • Low noise, strong anti-interference ability • Package size: 1.2×1.2×0.5mm	
MMC5983MA MMC3416xPJ	• Low temperature drift, low noise, low hysteresis, high accuracy • High reliability, good stability, strong anti-interference ability • MMC5983MA is AEC-Q100 Grade 2 certified • MMC3416xPJ has ultra-low power consumption, support up to 8 I²C addresses	

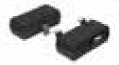
Hall Switch

Ultra-Low Power

Ultra Small Package Size
Multiple Package Types

Ultra-Wide Operation
Voltage Range

Accurate Switch Control
Multiple Package Types

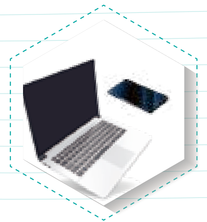
MHA100KN	• Omni polar and dual output, ultra-low power consumption, high sensitivity • Package size: DFN 4 1.0×1.4×0.37mm	
MHA150N/S	• Unipolar and single output, ultra-low power consumption, high sensitivity • Package size: SOT23-3L 2.9×1.6×1.1mm	
MHA160N/S	• Unipolar and single output, ultra-low power consumption, high sensitivity • Package size: SOT23-3L 2.9×1.2×0.55mm	
MHA183AS	• Unipolar and single output, ultra-low power consumption, high sensitivity • Package size: SOT23-3L 2.9×1.2×1.1mm	

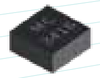
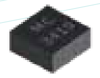
Capacitive Accelerometer & 6-Axis IMU

Low Power
Consumption

Ultra Small
Package Size

Multiple Functions &
Algorithm Support



MC3416	• 16-bit high resolution, support I²C communication mode • Low noise, low offset, low temperature drift • Package size: LGA-12 2×2×0.95mm	
MC3419 MC3479	• 16-bit high resolution, support I²C/SPI communication mode, with FIFO cache • Low noise, low offset, low temperature drift • Package size: LGA-12 2×2×0.95mm	
MC3630 MC3632 MC3635	• 14-bit resolution, support I²C/SPI communication mode, with FIFO cache • Ultra-low power consumption, supports a variety of low-power modes • Package size: LGA-12 2×2×0.95mm • MC3635 Package size: LGA-10 1.6×1.6×0.94mm	
MXC3500AL	• 16-bit resolution, support I²C/SPI communication mode • 1.5KB ultra-large FIFO cache, multiple low power modes • Single/double/triple tap break, step counter • Package size: LGA-12 2×2×0.73mm	
MIC61XX	• 16-bit high resolution, 3KB FIFO, support I²C/I3C/SPI communication mode, up to 2200Hz ODR • Gyro 0-rate offset +/-3%，offset over temperature +/-0.05dps/C, sensitivity error +/-1% • Package size: LGA 2.5×3×0.83mm	

Thermal Accelerometer

Monolithic
Integration

Extremely
Impact resistant

Ultra-Small Size

Ultra-Low
Temperaturedrift

MXC4005XC MXC6655XA	• 3-axis monolithic integration, wafer level package, ultra-small size, stable performance, low failure rate • Used in consumer electronic devices such as mobile phones and tablets • MXC4005XC Package size: 1.2×1.7×0.95mm • MMC5566XA Package size: 2×2×1mm	
MXR7150VW MXR7999VW	• 2-axis monolithic integration, the temperature compensations for the offset and sensitivity are done respectively, can be mounted flat or vertically, flexible installation • Analog output, MXR7999VW has +/- 2g range and 1000mV/g sensitivity • MXR7150VW has +/ -13.3g range and 150mV/g sensitivity • AEC-Q100 Grade 1 certified, widely used in active suspension, ESC and EPB systems • Package size: 5.5×5.5×2.7mm	
MXD2020EL MXD6235Q	• 2-axis, PWM digital output • Good consistency of offset and sensitivity, easy for temperature compensations • MXD2020EL has +/- 1g range and 0.2mg/ SQRT (Hz) noise • MXD6235Q has +/- 1.5g range and 0.13mg/ SQRT (Hz) noise • Used in level gauge, home appliance and other industrial applications • Package size: 5.5×5.5×2mm	
MXR7205VW	• 2-axis, the temperature compensations for the offset and sensitivity are done respectively, can be mounted flat or vertically, flexible installation. • SPI digital output, range +/- 5G, sensitivity 800LSB/g • AEC-Q100 Grade 2 certified, used in automotive ESC and EPB systems. • Package size: 5.5×5.5×2.7mm	

Image Stabilization Driver IC

MSD2100WA	• 10-bit DAC with ±100mA output current • Smart AAC(Automatic Actuator Control) algorithm embedded • Support I²C(1MHz)/I3C12.5MHz and 1.2V IO • Package size: 0.73 X 1.13 X 0.31mm (6-pin WLCSP)	
MSD4100WA	• Linear hall sensor and advanced PID embedded • Constant Current Linear Driver (1-ch, Imax = ±170mA) • Support I²C(3.4MHz)/I3C(12.5MHz) and 1.2V IO • Package size: 0.63 X 2.37 X 0.315mm (6-pin WLCSP)	NEW 即将上市